

## Electronic Patent Application Fee Transmittal

Application Number:	10644195
Filing Date:	20-Aug-2003
Title of Invention:	METHOD OF FORMING SILICON-CONTAINING INSULATION FILM HAVING LOW DIELECTRIC CONSTANT AND LOW FILM STRESS
First Named Inventor/Applicant Name:	Yasuyoshi Hyodo
Filer:	Katsuhiro Arai/Keiko Kinoshita (KOA)
Attorney Docket Number:	ASMJP.137AUS

Filed as Large Entity

### **Utility Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				1700